

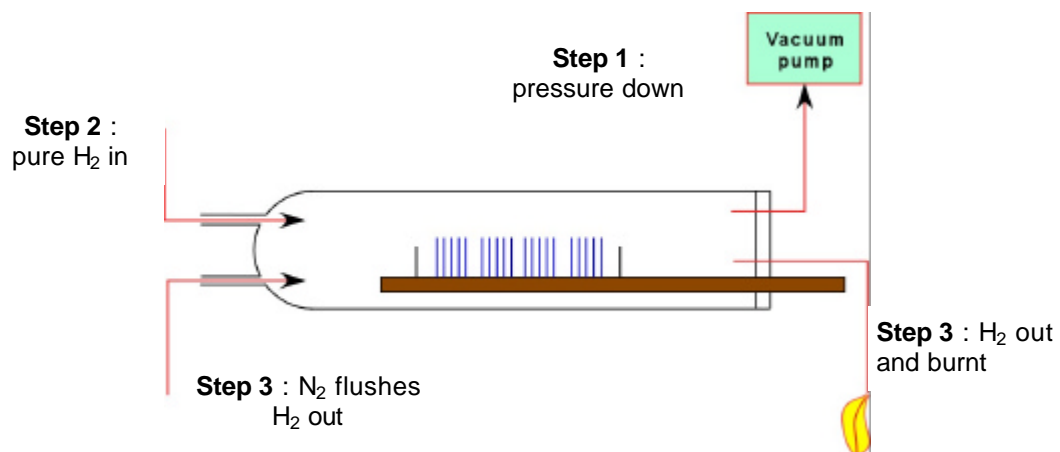
LYSINTER[®]

pure H₂ annealing process : Safe and highly efficient

Annealing process by pure H₂ is necessary in many key applications (Qss reduction, alloy no oxygen, crystal improvement, etc) but could not be implemented without seriously impacting the safety of the personnel.

The LYSINTER[®] process and reduced pressure system is the solution to combine maximum safety and maximum efficiency.

For instance, until today, the only way to neutralise Qss after photoresist plasma ashing was to repeat forming gas annealing several times. By using LYSINTER[®] pure H₂ annealing, one single operation is enough to reduce charge effects in an absolutely safe way.



Synoptic of a reduced pressure LYSINTER[®] process system

Features

- Includes maximum hardware safeties : LPCVD type leak tight tube, 1 continuous burner plus 1 process burner , UV flame detectors, vacuum pump, 4 digital pressure switches
- Includes gas system, tube, door closure with automatic safety lock.

Benefits

- ♦ **High efficiency : one annealing process step is enough**
- ♦ **Reduced pressure for a better process control and maximum safety**
- ♦ **Up to 200 wafers per run**
- ♦ **Adaptable to any kind of furnace and controller**
- ♦ **Available for up to 200 mm wafers**